
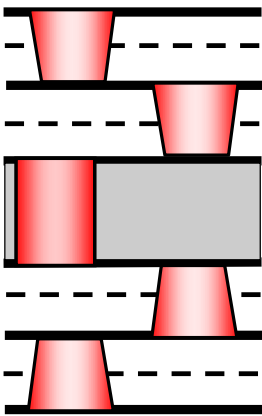


Build Up HDI (Standard)										
HDI06_2+2b+2_1,30_engl			6 - Layers							
			Core: 0,93 mm Cu 35/35 µm							
WE-Artikel No.:					2 + 2B + 2					
Customer:										
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE							[µm]	[µm]	
	TOP/VS				Foil	12 µm	1)	12		
							1 x 1080	60		
	2				Foil	12 µm		30		
							1 x 1080	55		
	3					12 µm		35		
		0,930 mm			930					
	4		12 µm		35					
				1 x 1080	55					
	5	Foil	12 µm		30					
				1 x 1080	60					
	BOT/RS	Foil	12 µm	1)	12					
		1) copper thickness outer layers: appr. 55 µm								
		total material thickness: 1314								
		Note: Lamination thickness for Prepregs depending on layout characteristics.								
final lamination thickness:		1,30	+/-	0,11	mm	Date:		Engineer:		
thickness with electro plated Cu:		1,39	+/-	0,14	mm					
total thickness with soldermask		1,45	+/-	0,16	mm					
customer requirement			+/-		mm	point:				
prepared: on 05.01.2006 by S. Keller			checked: on 04.05.2006 by M.Kress			approved: on 05.01.2006 by R. Schönholz			revision 00	
									page: 17+	